

REMARKS

The Office Action of June 16, 2005 has been received and its contents carefully considered.

The present Amendment revises claims 21-23 and cancels claims 24-26. The modifications to claim 21 (the sole independent claim) and self-alignment when the components are not completely aligned to begin with, and this is supported (for example) by the passage at page 20 of the application, lines 2-10. The modifications to claim 21 also include filling a gap between the components with resin. This is supported (for example) by Figure 1 of the application's drawings.

The Office Action rejected two of the claims for anticipation by Dalal et al, and the rest of the claims for obviousness based on Dalal et al in view of Davis et al. These references will hereafter be called "Dalal" and "Davis." For the reasons discussed below, it is respectfully submitted that the claims are patentable over Dalal and Davis.

In Figure 4 of the Dalal reference, a chip 30 is mounted on a circuit card that is coated with an insulator material 22. However, the reference neither discloses nor suggests a step of "filling an insulating resin into a gap between said first semiconductor chip or substrate and said second semiconductor chip after they are joined," as is now recited in claim 21.

The Davis reference discloses the use of tin on gold. However, there is no suggestion here of either self-alignment or filling a gap between two self-aligned components with insulating resin.

Since the remaining claims depend from independent claim 21 and recite additional limitations to further define the invention, they are patentable along with claim 21 and need not be further discussed.

For the foregoing reasons, it is respectfully submitted that this application is now in condition for allowance. Reconsideration of the application is therefore respectfully requested.

Respectfully submitted,



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